



The Parofluor ULTRA™ materials cover the majority of application requirements within the semiconductor industry including high purity, high temperatures up to 320°C (608°F), and broad chemical compatibility. Parofluor ULTRA™ offers many advantages to the semiconductor seal designer in the following areas:

	<ul style="list-style-type: none"> • Improved compression set • Improved compressive stress relaxation (retained resiliency) • Improved plasma and chemical resistance • Low particle generation • Improved thermal stability • Low outgassing • Low permeation • Low weight loss under high vacuum
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All Parofluor materials are manufactured exclusively within our ULTRA™ High Purity manufacturing cell. Here, care is taken to manufacture the product within our clean manufacturing systems. Parker Parofluor ULTRA™ materials are available in the following forms:

	<ul style="list-style-type: none"> • O-Ring Seals • Sheets/Slabs • Custom Molded Shapes • Press-in-Place Seals • Composite Seals (rubber bonded to metal)
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These products are an ideal choice in applications such as door seals, chamber lid seals, valve seals, flanges, mass flow controls, windows and quartz tubes.

Parker Compound	Color	Normal Hardness (Shore A)	Temperature Range	Feature	General Application
FF200-75	Black	75	15 °C to 320 °C 5°F to 608°F	High temperature low compression set chemical resistance	Ion Implant, Metal CVD, Sputtering (PVD), Diffusion Furnaces, LPCVD, RTP, Wafer Etch, Cleaning, Rinsing, Stripping, UPDI
FF350-75	White	75	-15 °C to 316 °C 5 ° F to 600 ° F	High purity High temperature	Ion Implant, Metal CVD, Sputtering (PVD), Diffusion Furnaces, LPCVD, RTP, APCVD, HDPCVD, PCVD, Ashing, Plasma Etch, Plasma Strip
FF500-75	Black	75	-15 °C to 275 °C 5 °F to 5 25°F	Chemical resistance	Ion Implant, CVD, Sputtering (PVD), Diffusion Furnaces, LPCVD, RTP, Water Etch, Cleaning, Rinsing, Stripping, UPDI
FF700-60	Translucent	60	-15°C to 260°C 5 ° F to 500 ° F	ULTRA™ high purity	Ion Implant, CVD, Sputtering (PVD), Diffusion Furnaces, LPCVD, RTP, Water Etch, Cleaning, Rinsing, Stripping, UPDI where ULTRA™-high purity is required